

# Connector for CMOS Camera Module

SCKA Series



Compact size achieved from thin body-forming molding.

For  
SD Memory  
Card

For  
microSD™  
Card

For  
SIM Card  
8pins

For  
W-SIM

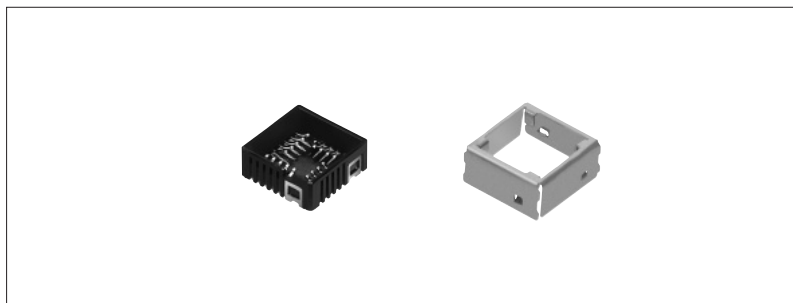
For  
Memory  
Stick Micro™

For  
Memory  
Stick™

Combine Type

For  
Compact  
Flash™

For CMOS  
Camera Module



## Typical Specifications

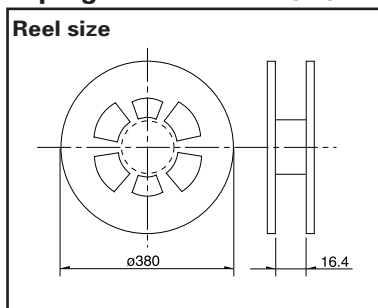
Items		Specifications
Dimensions	6×6mm module type	7×7×3.1mm
Structure	Mounting system	Surface mounting type
Performance	Operating temperature range	-25°C to +85°C
	Voltage proof	100V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycles	10cycles

## Product Line

Items	Product	Packing system	Minimum packing unit (pcs.)	Product No.	Drawing No.
6×6mm module type	Connector	Taping	2,000	SCKA2A0100	1
	Cover	—	5,000	JSCKA0002A	2

## Packing Specifications

Taping Unit:mm



Product No.	Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing		
SCKA2A0100	2,000	4,000	12,000	16	420×410×187

## Bulk

Product No.	Number of packages (pcs.)		Export package measurements (mm)
	1 case /Japan	1 case /export packing	
JSCKA0002A	5,000	10,000	400×288×161

■ Dimensions  
6×6mm module type

Unit:mm

No.	Style	
1	Connector	
	PC board mounting hole dimensions (Viewed from the mounting face side)	
2	Style	Connector/Cover combination diagram (Reference)
	Cover	

For  
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8pins

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For  
Memory  
Stick Micro™

For  
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Combine Type

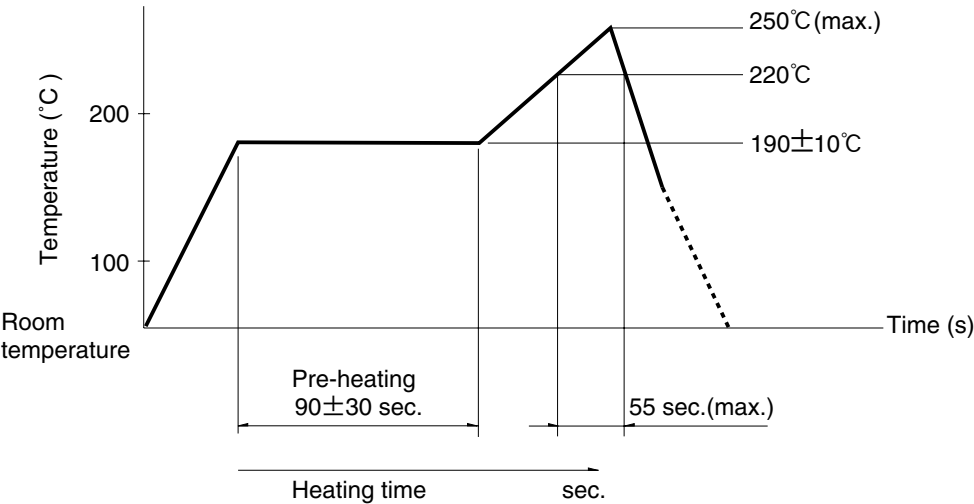
For  
Compact  
Flash™

For CMOS  
Camera Module

## Soldering Conditions

### Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
- 3. Temperature profile



## Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. When soldering, do not use water soluble flux because this may corrode the product.
- 3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
- 4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.